

VERTICAL REMOVAL OF EXCESS SOLDER FROM A CIRCUIT SUBSTRATE

5

ABSTRACT

A method for vertical removal of excess solder from a circuit substrate includes the use of a sacrificial circuit substrate with a plurality of pads and vias that are solder-wettable. The pads and vias of the sacrificial circuit substrate are placed in vertical proximity to the excess solder of the circuit substrate. The excess solder is heated until it is liquid, wherein the excess solder is wicked vertically onto the pads and into the vias of the sacrificial circuit substrate. Thereafter, the sacrificial circuit substrate is lifted from the proximity of the circuit substrate while the solder is in a liquid, taking the excess solder with it but leaving a predetermined amount on the circuit substrate.